

**Sample A: For general position**

Mr. Simon Wong  
Human Resources Manager  
The Hong Kong and Shanghai Banking Corporation

1st May 2020

Dear Mr Wong, (if you don't know the name, write "Dear Sir/Madam)

**Re: Application for the position of Management Trainee**

I am writing in response to your SCMP advertisement dated 1<sup>st</sup> April, 2020. I graduated from City University of Hong Kong with a BBA degree. With substantial practical experience in commercial market, I am confident to submit my application and CV for the Management Trainee position.

My internship experience in Singapore this year laid a solid foundation to consolidate my knowledge into practice. In this project, I reviewed the Premium Account service chain for Bank of Singapore (Head Office) under the supervision of the Retail Banking Manager. I demonstrated my leadership skills in communicating and aligning stakeholders with diversified interests. Result was fruitful that I delivered a 50-page service manual on how to streamline the workflow and to complete the account opening process in 5 minutes time.

At university, I was a committed member in the Business Society. I supervised a team of 10 members in planning and organizing events and projects. I am an effective facilitator for decision making. My supportive attitude always generates positive dynamic in teams.

It is my greatest pleasure to attend an interview and describe how I can contribute to your esteemed corporation in details. Looking forward to receiving your reply soon.

Yours sincerely, (if you start with Dear Sirs, write "Yours faithfully" here)

*Linda Chan*

Chan Lok Tze, Linda (signature or e-signature)

Tel: 9090 9090 / email: [loktze111@gmail.com](mailto:loktze111@gmail.com)

**Sample B: For engineering/STEM position**

[Date]

[Name of HR Manager]

[Company Name]

[Company Address]

Dear Sir/Madam,

**RE: Application for the position of Engineering Trainee**

I am writing to express my interest in the job opening for the Engineering Trainee position posted in Jobsdb.com on 20 Aug, 2020. I shall graduate from City University of Hong Kong with a degree in Mechanical Engineering this July, and with my academic background, skills and personalities, I believe that I am an excellent fit for the position.

I have acquired a sound overall knowledge of leading-edge engineering principles, tools, and practices, with emphasis on designing, building and testing of mechanical systems, and am proficient in the application of various automated solutions including current releases of AutoCAD and SolidWorks. I have applied classroom learning to innovative and successful projects in which I served as sole or principal designer.

In my previous internship experience, I have been a responsible junior leader and have a track record of completing assignments in good quality and in a timely manner. I also demonstrate leadership, sound judgment, creativity, analytical and problem solving skills., and interact productively with people from diverse backgrounds.

I am confident that I could make valuable contributions to your organization, and I would welcome the opportunity to meet with you to discuss how my abilities might best be employed by your organization. I can be reached at 9111 2222 or by email [tomwong\\_88@gmail.com](mailto:tomwong_88@gmail.com).

Looking forward to receiving your reply soon.

Yours faithfully, (if you start with Dear Ms. Chan, write "Yours sincerely" here)

*Tom Wong* (e-signature or signature)

Wong Tai Ming, Tom